



IPW  
PATENT  
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Hirokazu HONDA

Confirmation No. 7187

Serial No. 09/678,609

GROUP 2827

Filed October 4, 2000

Examiner David E. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR  
DEVICE HAVING THE SAME, AND METHOD OF FORMING  
THE SAME AS WELL AS METHOD OF MOUNTING THE  
SEMICONDUCTOR CHIP ON THE INTERCONNECTION BOARD

**RESPONSE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 3, 2004

Sir:

In response to the communication of July 28, 2004,  
consideration of the response filed on May 11, 2004 is  
respectfully requested.

**Remarks** begin on page 2 of this paper.